

JOCHC15B

	Common Mode Transient Immunity at Logic High	CM _H	I _F =0mA, V _{CM} =1000Vpp, C _L =15pF, V _{CC} =5V	20	-	-	kV/μs
	Common Mode Transient Immunity at Logic Low	CM _L	I _F =7mA, V _{CM} =1000Vpp, C _L =15pF, V _{CC} =5V	20	-	-	kV/μs
	Output Rise Time	t _r	I _F =7mA,C _L =15pF	-	10	-	ns
	Output Fall Time	t _f		-	10	-	

Recommended Operating Conditions

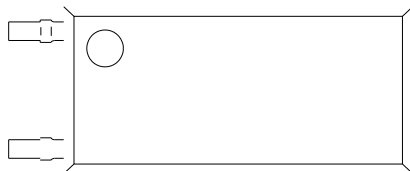
Characteristics	Symbol	Min.	Typ.	Max.	Unit
Operating Temperature	T _a	-40	-	105	
Supply Voltage	V _{CC}	2.7	-	5.5	V
Low Level Input Current	I _{FL}	0	-	250	μA
High Level Input Current	I _{FH}	8	-	I	

ORDERING INFORMATION

<p>J</p> <p>JieJie Microelectronics Co., Ltd.</p>	<p>OC</p> <p>Opto Coupler</p>	<p>H</p> <p>High speed</p>	<p>C</p> <p>Single CMOS Inverting Push-Pull</p>	<p>1</p> <p>3V V_{CC} 7V</p>	<p>5</p> <p>15MBd high speed</p>	<p>B</p> <p>I_{FT} 5mA</p>	<p>-L5X</p> <p>15MBd high speed</p>	<p>/</p> <p>None:T1 R:T2 None:LSOP5 W:LSOP5W</p>
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Packing Quantity	
Option	Quantity
None/R	3000 Units/Reel

MARKING



Characteristics Curves

FIG.1: Forward Current vs. Forward Voltage

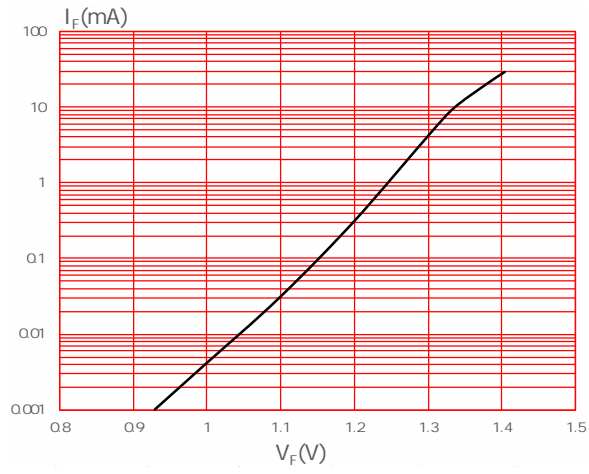


FIG.2: Max. Allowable LED Forward Current vs. Ambient Temperature

FIG.7: Propagation Delay vs. Ambient Temperature

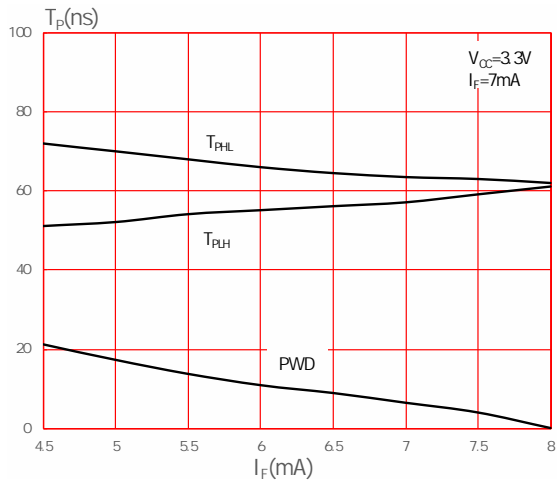


FIG.8: Propagation Delay vs. Ambient Temperature



Package Dimension (Unit: mm)

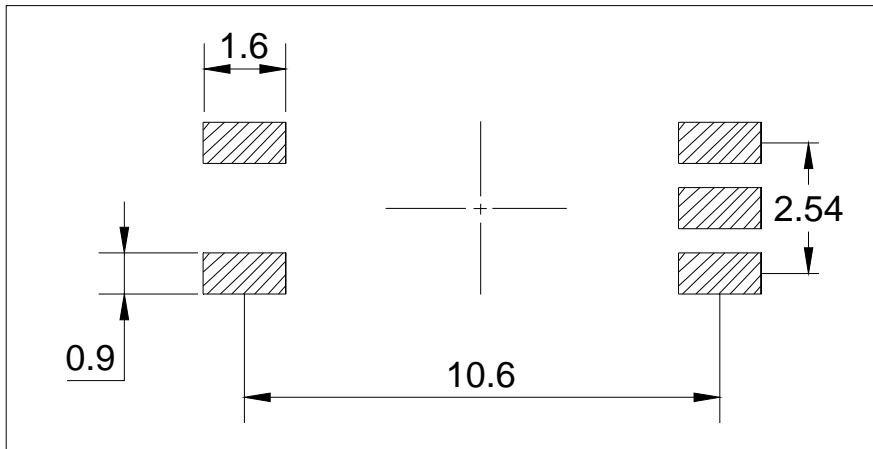
LSOP5



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	7.40		7.80	0.291		0.307
B	3.40		3.80	0.134		0.150
C	0.00		0.20	0.000		0.008
D	1.80		2.20	0.071		0.087
E	8.10		8.70	0.319		0.343
F	0.40		1.00	0.016		0.039
G	9.90		10.50	0.390		0.413
H	0.10		0.30	0.004		0.012
I	1.80		2.40	0.071		0.094
J	0.25		0.55	0.010		0.022
K						

RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)

LSOP5

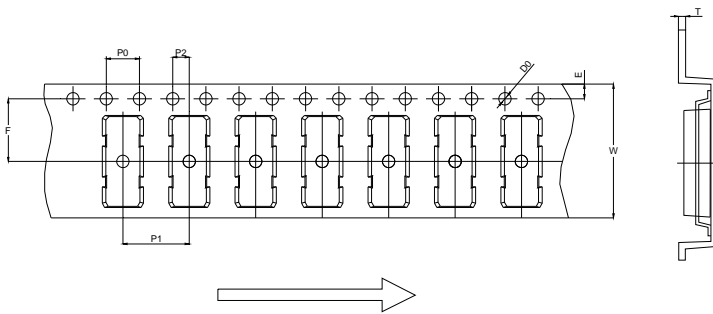


LSOP5W

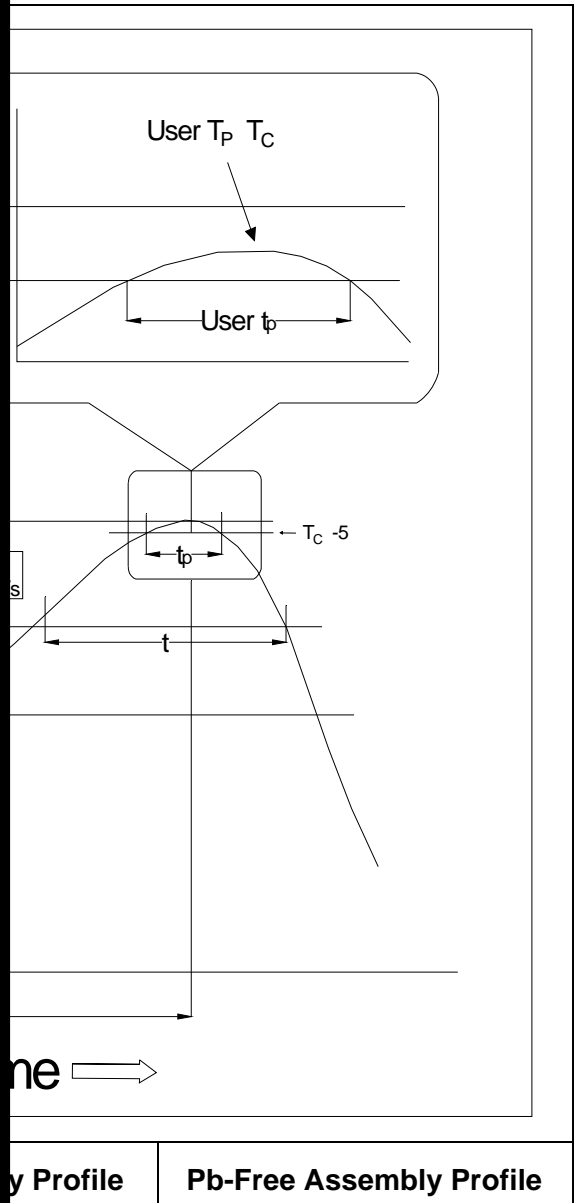


CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option None/R



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0	1.50	1.55	1.60	0.059	0.061	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.80	16.00	16.20	0.622	0.630	0.638



Profile


Pb-Free Assembly Profile

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life of one year when stored under standard conditions.
6. Recommend storage Temp.: 0~40°C;
Recommend storage humidity: <60%;
MSL level: MSL 1

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